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No.	Publication No.	Title
1.	<u>2003 - 276060</u>	INJECTION MOLDING DIE AND PIN THEREFOR
2.	<u>2003 - 136217</u>	EJECTION PIN FOR VACUUM DIE CASTING
3.	<u>2002 - 239707</u>	DIE CASTING APPARATUS
4.	<u>2001 - 200361</u>	OBSERVATORY APPARATUS IN HOT VACUUM VAPOR DEPOSITION APPARATUS
5.	<u>11 - 354616(1999)</u>	CHIP EJECTING DEVICE
6.	<u>11 - 026667(1999)</u>	MANUFACTURE OF SEMICONDUCTOR DEVICE
7.	<u>10 - 197700(1998)</u>	ELECTRON-BEAM IRRADIATION METHOD AND OBJECT IRRADIATED WITH ELECTRON BEAM
8.	<u>10 - 189511(1998)</u>	WAFER CLEANING DEVICE
9.	<u>10 - 048136(1998)</u>	METHOD AND APPARATUS FOR ANALYZING GAS ELEMENT
10.	<u>09 - 235676(1997)</u>	PLASMA TREATMENT AND PLASMA TREATING DEVICE
11.	<u>09 - 229563(1997)</u>	CASTING MACHINE
12.	<u>09 - 193174(1997)</u>	APPARATUS FOR EXTRACTING ELASTIC MOLDED PRODUCT AND METHOD
13.	<u>09 - 068808(1997)</u>	PHOTOCOMPOSING MACHINE
14.	<u>09 - 022665(1997)</u>	X-RAY IMAGE PICKUP TUBE AND MANUFACTURE THEREOF
15.	<u>07 - 316950(1995)</u>	EJECTION DEVICE FOR FLOAT WEFT
16.	<u>05 - 024080(1993)</u>	INJECTION MOLDING MOLD AND INJECTION MOLDING METHOD
17.	<u>04 - 336218(1992)</u>	MOLD
18.	<u>03 - 291389(1991)</u>	PLASMA TREATING DEVICE
19.	<u>03 - 254921(1991)</u>	INJECTION MOLD
20.	<u>03 - 254920(1991)</u>	INJECTION MOLD
21.	<u>03 - 161156(1991)</u>	VACUUM DIE CASTING MACHINE
22.	<u>02 - 258236(1990)</u>	MOLDING METHOD OF SHORT-FIBER-REINFORCED RESIN
23.	<u>01 - 320117(1989)</u>	SYNTHETIC RESIN MOLDING EQUIPMENT
24.	<u>01 - 109737(1989)</u>	CHUCKING DEVICE AND METHOD FOR REMOVING WAFER TO BE CUT OFF FROM LARGE DIE
25.	<u>63 - 264320(1988)</u>	METHOD AND APPARATUS FOR MOLDING DISC
26.	<u>63 - 210932(1988)</u>	COMPOSER
27.	<u>60 - 116421(1985)</u>	EXTRACTING DEVICE FOR MOLDED PART
28.	<u>58 - 197734(1983)</u>	MOLD PRODUCT LOADING/UNLOADING APPARATUS
29.	<u>58 - 059826(1983)</u>	RESIN CASING FOR VACUUM CLEANER OR THE LIKE

30. 57 - 160561(1982) VACUUM DIE CASTING METHOD

31. 57 - 160560(1982) PRESSURE CASTING DEVICE

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L Number	Hits	Search Text	DB	Time stamp
23	23	(vacuum suct\$3) adj nozzle with	USPAT;	2004/03/11
		(resilient flexible) adj material	EPO; JPO	17:19
24	469	(vacuum suct\$3) adj nozzle with	USPAT;	2004/03/11
		(resilient flexible rubber)	EPO; JPO	17:20
26	1	(vacuum suct\$3) adj (tip nozzle) with	USPAT;	2004/03/11
		(resilient flexible rubber) and eject\$3	EPO; JPO	17:21
		adj pin		
27	1	(vacuum suct\$3) near (tip nozzle) with	USPAT;	2004/03/11
		(resilient flexible rubber) and eject\$3	EPO; JPO	17:21
		adj pin		
28	12	(vacuum suct\$3) near (tip nozzle) with	USPAT;	2004/03/11
		(resilient flexible rubber) and wafer	EPO; JPO	17:35
31	13	(vacuum suct\$3) near (tip nozzle) with	USPAT;	2004/03/11
		(resilient flexible rubber) and die	EPO; JPO	17:36
32	603	(vacuum suct\$3) near (tip nozzle) with	USPAT;	2004/03/11
		(resilient flexible rubber)	EPO; JPO	17:37
33	10	264/\$.ccls. and (vacuum suct\$3) near (tip	USPAT;	2004/03/11
		nozzle) with (resilient flexible rubber)	EPO; JPO	17:37
34	21	29/\$.ccls. and (vacuum suct\$3) near (tip	USPAT;	2004/03/11
		nozzle) with (resilient flexible rubber)	EPO; JPO	17:38
35	124	(vacuum suct\$3) near (tip nozzle) with	USPAT;	2004/03/11
		rubber	EPO; JPO	17:44
36	76	(vacuum suct\$3) near (tip nozzle) with	USPAT;	2004/03/11
		resilient	EPO; JPO	17:44
37	33	(vacuum suct\$3) near (tip nozzle) same	USPAT;	2004/03/11
		resilient adj material	EPO; JPO	17:45
38	45	(vacuum suct\$3) near (tip nozzle) same	USPAT;	2004/03/11
		flexible adj material	EPO; JPO	17:50
39	58	(vacuum suct\$3) near (tip nozzle) same	USPAT;	2004/03/11
		(soft resilieant flexible) adj material	EPO; JPO	17:51
-	277	chen.in. and wafer.ti.	USPAT;	2004/01/09
			US-PGPUB;	10:50
			EPO; JPO	
-	104	(chen.in. and wafer.ti.) and separat\$3	USPAT;	2004/01/09
		and semiconductor	US-PGPUB;	10:51
			EPO; JPO	
-	4	((chen.in. and wafer.ti.) and separat\$3	USPAT;	2004/01/09
		and semiconductor) and tether	US-PGPUB;	10:51
			EPO; JPO	
-	9	thin adj die same separat\$3 and vacuum	USPAT;	2004/03/06
			EPO; JPO	13:02
-	495	die same separat\$3 and vacuum same wafer	USPAT;	2004/03/06
			EPO; JPO	13:28
-	2	(die same separat\$3 and vacuum same	USPAT;	2004/03/06
		wafer) and tether	EPO; JPO	13:04
-	62	(die same separat\$3 and vacuum same	USPAT;	2004/03/06
		wafer) and clamp\$3 and moving	EPO; JPO	13:04
-	172	die same separat\$3 and vacuum and support	USPAT;	2004/03/06
		same wafer and (clamp\$3 hold\$3) and	EPO; JPO	13:29
		(moving transfer\$3)		
-	12	(die same separat\$3 and vacuum and	USPAT;	2004/03/06
		support same wafer and (clamp\$3 hold\$3)	EPO; JPO	13:30
		and (moving transfer\$3)) and eject\$3 with		
		pin		
-	17	("1179482" "2647578" "3493155"	USPAT	2004/03/10
		"3507426" "3562057" "3562058"		11:26
		"3565306" "3677875" "3678550"		
		"3790051" "4140260" "4296542"		
		"4706370" "4775085" "5104023"		
		"5227001" "5710065").PN.		
-	4	wafer with die and vacuum and ejection	USPAT;	2004/03/10
		adj pin	EPO; JPO	11:31
-	2	thin adj die and vacuum and ejection adj	USPAT;	2004/03/10
		pin	EPO; JPO	11:32
-	32	position\$3 and clamp\$3 and moving and	USPAT;	2004/03/10
		vacuum and ejection adj pin	EPO; JPO	11:35
-	0	downward with vacuum and ejection adj pin	USPAT;	2004/03/10
			EPO; JPO	11:35

-	0	down\$ward with vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:35
-	1	breaking same vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:36
-	1	tether and vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:37
-	14	29/\$.ccls. and vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:38
-	11	257/\$.ccls. and vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:39
-	5	438/\$.ccls. and vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:40
-	12	(nozzle tip) with (suction vacuum) and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:40
-	50	4494902.URPN.	USPAT	2004/03/10 11:44
-	26	5169196.URPN.	USPAT	2004/03/10 13:31
-	9	("4667402" "4859269" "4874444" "4990051" "5169196" "5351872" "5447266" "5589029" "6201306").PN.	USPAT	2004/03/10 13:32
-	9	5960260.URPN.	USPAT	2004/03/10 13:36
-	6	("4664739" "4793883" "5194934" "5237205" "5444301" "5504374").PN.	USPAT	2004/03/10 13:41
-	7	4876791.URPN.	USPAT	2004/03/10 13:41
-	14	("3632955" "3902148" "3946931" "3949925" "3958740" "4010885" "4135630" "4151945" "4166562" "4270649" "4372802" "4498023" "4500032" "4510683").PN.	USPAT	2004/03/10 13:42
-	50	4494902.URPN.	USPAT	2004/03/10 13:45
-	6	("3274038" "3785507" "3793123" "4290732" "4375126" "4410103").PN.	USPAT	2004/03/10 13:47
-	1	6205745.URPN.	USPAT	2004/03/10 13:48
-	3	("4494902" "5203143" "5319846").PN.	USPAT	2004/03/10 13:48
-	0	6190115.URPN.	USPAT	2004/03/10 13:48
-	3	("4494902" "5310301" "5348316").PN.	USPAT	2004/03/10 13:49
-	1	5966903.URPN.	USPAT	2004/03/10 13:49
-	3	("4494902" "5203143" "5319846").PN.	USPAT	2004/03/10 13:49
-	35	4740136.URPN.	USPAT	2004/03/10 13:50
-	2	("3906614" "4494902").PN.	USPAT	2004/03/10 13:52
-	4	5589029.URPN.	USPAT	2004/03/10 13:52
-	3	("4850780" "4859269" "5348316").PN.	USPAT	2004/03/10 13:53
-	3	("4850780" "4859269" "5348316").PN.	USPAT	2004/03/10 13:53
-	21	4166562.URPN.	USPAT	2004/03/10 13:54
-	11	("3442432" "3465408" "3593404" "3689991" "3724068" "3859718" "3887783" "3911568" "3949925" "4003125" "4010885").PN.	USPAT	2004/03/10 13:56
-	18	3887783.URPN.	USPAT	2004/03/10 13:56
-	5	5120391.URPN.	USPAT	2004/03/10 13:59
-	5	("3937386" "3941297" "4050618" "4166562" "4526646").PN.	USPAT	2004/03/10 13:59

-	5	("4555876" "4749329" "4851902" "4978253" "5549716").PN.	USPAT	2004/03/10 14:00
-	3	5987722.URPN.	USPAT	2004/03/10 14:01
-	5	5120391.URPN.	USPAT	2004/03/10 14:02
-	8	5660318.URPN.	USPAT	2004/03/10 14:02
-	4	("4051508" "4060828" "4244002" "5120391").PN.	USPAT	2004/03/10 14:03
-	4	("4051508" "4060828" "4244002" "5120391").PN.	USPAT	2004/03/10 14:03
-	5	("3937386" "3941297" "4050618" "4166562" "4526646").PN.	USPAT	2004/03/10 14:03
-	124	separating and vacuum and eject\$3 adj pin	USPAT; EPO; JPO	2004/03/10 14:16
-	18	separating same wafer and (suction vacuum) and (push\$3 eject\$3) adj pin	USPAT; EPO; JPO	2004/03/10 14:19
-	62	(extract extracting separating) same (die chip ic) and (suction vacuum) and (push\$3 eject\$3) adj pin	USPAT; EPO; JPO	2004/03/10 14:20
-	3	("6297075" "6337258" "6429506").PN.	USPAT	2004/03/10 14:21
-	6	("5152707" "5516125" "5738165" "5932065" "5938211" "6032715").PN.	USPAT	2004/03/10 14:21
-	1	6427539.pn.	USPAT; EPO; JPO	2004/03/10 16:31
-	0	6427539.URPN.	USPAT	2004/03/10 16:31
-	12	("3761784" "4191057" "4275406" "4317126" "4444054" "4683755" "4986861" "4996627" "5356176" "5629486" "5644102" "5917264").PN.	USPAT	2004/03/10 16:31
-	42	4317126.URPN.	USPAT	2004/03/10 16:31
-	7	("3801949" "3858150" "4127840" "4203327" "4317126" "4456901" "4510671").PN.	USPAT	2004/03/10 16:32
-	9	4651120.URPN.	USPAT	2004/03/10 16:32
-	9	("3626096" "3663768" "3772133" "3991285" "4491697" "4651120" "4783821" "4993072" "5146435").PN.	USPAT	2004/03/10 16:33
-	10	5490220.URPN.	USPAT	2004/03/10 16:33
-	13	("2425481" "3588382" "4063050" "4234811" "4310906" "4321432" "4701640" "4730283" "5255246" "5490220" "5548658" "6169810" "6178249").PN.	USPAT	2004/03/10 16:34
-	0	6532293.URPN.	USPAT	2004/03/10 16:34
-	0	6532293.URPN.	USPAT	2004/03/10 16:34
-	10	5490220.URPN.	USPAT	2004/03/10 16:35
-	9	4651120.URPN.	USPAT	2004/03/10 16:35
-	7	("3801949" "3858150" "4127840" "4203327" "4317126" "4456901" "4510671").PN.	USPAT	2004/03/10 16:36
-	13	4275406.URPN.	USPAT	2004/03/10 16:36
-	6	("3758830" "3761784" "3893228" "4125820" "4131524" "4204185").PN.	USPAT	2004/03/10 16:36